ABSTRACT

A modularized probe head for modularly assembling on a probe card is configured for probing a semiconductor wafer under test. The probe head includes a silicon substrate having an active surface and an opposing back surface. The back surface of the silicon substrate is attached on a holder. The silicon substrate has a plurality of peripheral bond pads and contact pads on its active surface. At least a probing chip is mounted on the active surface of the silicon substrate. The probing chip has probing tips and side electrodes. The side electrodes are connected with the contact pads by means of solder material. The peripheral bonding pads of the silicon substrate are connected with a flexible printed circuit for electrically connecting to a multi-layer printed circuit board of a probe card.